

Electronic Acknowledgement Receipt

EFS ID:	8698998
Application Number:	09523990
International Application Number:	
Confirmation Number:	6138
Title of Invention:	Method of manufacture and identification of semiconductor chip marked for identification with internal marking indicia and protection thereof by non-black layer and device produced thereby
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Ashley Campbell
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0026
Receipt Date:	25-OCT-2010
Filing Date:	13-MAR-2000
Time Stamp:	20:53:30
Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$940
RAM confirmation Number	9701
Deposit Account	502624
Authorized User	
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part/.zip	Pages (if appl.)
1	Transmittal Letter	085027_0026_tm.pdf	22225 35af365034e2bb8d808044dc6300286725eb1ef5	no	1

Warnings:

Information:

2	Request for Continued Examination (RCE)	085027_0026_rce.pdf	37324 a89f952d5ef3cb551dd6fc54e089931d5bfe76	no	1
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Warnings:

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Information:

3	Transmittal Letter	085027_0026_ids.pdf	23396 8ec5e52fbff3ba641fb10aee24fbff1c1b39986a9	no	2
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Warnings:

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4	Information Disclosure Statement (IDS) Filed (SB/08)	085027_0026_idslist.pdf	63696 576ec1a1b70809012a1594d175c341b1def169700	no	3
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Information:

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5	Request for Corrected Filing Receipt	085027_0026_FRequest.pdf	24145 070cef28a7221499be0f0e0cfa4237fd3a79525e8	no	2
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Warnings:

Information:

6		085027_0026_amendment.pdf	85899 0ecf7b519864327bd4d799676d8f7fa58e006	yes	12
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Multipart Description/PDF files in .zip description

Document Description	Start	End
Amendment Submitted/Entered with Filing of CPA/RCE	1	1
Claims	2	4

	Applicant Arguments/Remarks Made in an Amendment			5	12			
Warnings:								
Information:								
7	NPL Documents	1.pdf	2254221 072127b124142b87d448b36305577e06d72 81092	no	4			
Warnings:								
Information:								
8	NPL Documents	2.pdf	3696109 daa11204b119d03a708a79af619f46550 ab74	no	9			
Warnings:								
Information:								
9	NPL Documents	3.pdf	4517666 1a140fbdb7c9b154f7370fa4bc4129a4c8aa aab74	no	7			
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10	NPL Documents	4.pdf	885848 2895c75eb4f536c72064f35a1853c2a9776 ab65	no	6			
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11	NPL Documents	5.pdf	717153 6ca9b2a4fc3f93cd5e8d84fc4bb8318ea a26a	no	5			
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12	NPL Documents	6_HU_Copper_Polymide.pdf	436455 a0f0baecc448865a251da92121b117fe2 a7af5	no	7			
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13	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 81120377462423e7e041aef39c24a5e4578 ab27	no	8			
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14	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a72602225181358d0292129de7b292d594 1d614	no	4			
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15	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab7fbca8408720a04fe947e4d45e395 eefb5	no	4
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16	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 950160bd4c3091b1b797ed0026a7b2bc 14322	no	4
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17	NPL Documents	11_VENKATESAN_A_High_performance_1_8V.pdf	618169 7bc31a0bbec9891b111026e5bc76090c 5a8d	no	4
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18	NPL Documents	12_JENEI_HighQ_Inductors.pdf	279415 1249e78d1bf0be1cc04f0724c372)ffef b811	no	3
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19	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGe_BiCMOS_process.pdf	420788 8e2629669459e3e0d15bd587c4a33599 f60e	no	4
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20	NPL Documents	14_SAKRAN_implementation_of_65nm.pdf	1254646 3d460954664f71b427310836837b22ae0 8c5a1	no	3
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21	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 c0afeada905c311c1691a55df9d8117930f44 7f	no	2
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23	NPL Documents	17_PDF_BOHR_plenary_paper_Intel_ISSCC_09_pdf.pdf	1615786 d137856a9834b4617c15834bcad224af58 acc3	no	6
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24	NPL Documents	18_PDF_INGERLY_Low_K_Interconnect_IEEE_2008_pdf.pdf	651359 de1a1dtech/190914c509876a9b7e88110972a5b	no	3
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25	NPL Documents	19_PDF_KURD_Next_generation_intel_2008_pdf.pdf	259226 1ba8d2c1bc024ecf5924c5b2be99ec098a456c4a	no	2
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26	NPL Documents	20_PDF_MALONEY_Novel_clamp_circuits_for_IC_power_supply_protection_pdf.pdf	191082 ea0ab46b342e1b16beda2955b6297276ab1e41cf7	no	12
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27	NPL Documents	21_PDF_GEFFKEN_Overview_of_polyimide_pdf.pdf	851514 e1bb1445fbff5b540007fa17563977e5306a5274ea	no	11
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28	NPL Documents	22_PDF_LUTHER_Planar_Copper_pdf.pdf	2095781 90ab029bf75ef94670b563e761b92e1c2d88276ca	no	8
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29	NPL Documents	23_PDF_MASTER_Ceramic_Ball_Grid_Array_pdf.pdf	1069512 b1e1e0156a013147b2766b118011a610f5586e	no	5
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30	NPL Documents	24_PDF_MALONEY_Stacked_P_MOS_clamps_for_high_voltage_power_supply_protection_pdf.pdf	1327621 bf725db30d1b90a2a26a150143632508a1bd488	no	8
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32	NPL Documents	26_PDF_MEGICA_Brochure_leaflets_01_28_04_pdf.pdf	888383 acc30115e57db17d33ad9f52144d0fbfc181f689a	no	3
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33	NPL Documents	27_PDF_LIN_Post_Passivation_Technology_Presentation_for_TSMC_Tech_Symposium_2003.pdf.pdf	1277639 20556e2754a28ff03ec295bcc5e8f724d52717e69	no	32
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34	NPL Documents	28_PDF_LIN_A_New_IC_Connection_Scheme_and_Design.pdf.pdf	116206 a1e1bb4b5cc0907c706677910a64710cc088	no	4
Warnings:					
Information:					
35	Fee Worksheet (PTO-875)	fee-info.pdf	32033 1a12e8f70aef1ac536754d55e9344f14ebc9e82	no	2
Warnings:					
Information:					
Total Files Size (in bytes):				41064693	
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p>New Applications Under 35 U.S.C. 111 If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p>National Stage of an International Application under 35 U.S.C. 371 If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p>New International Application Filed with the USPTO as a Receiving Office If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					